AMENDMENTS TO THE CLAIMS

The following is a complete listing of the claims, which replace all previous versions of the claims.

- 1. (Previously Presented) An attachment system for a modular component of an electronic device, comprising:
 - a latch member configured for securing the modular component to the electronic device; and
 - a release member movably coupled to the latch member, wherein the release member comprises a grip configured for bending the release member to effectuate a movement of the latch member to a released position.
- 2. (Previously Presented) The attachment system of claim 1, wherein the latch member comprises a flexible portion that is inwardly bendable with bending of the release member.
- 3. (Original) The attachment system of claim 2, wherein the latch member comprises a fixed end and a free end adjacent the flexible portion.
- 4. (Original) The attachment system of claim 3, wherein the latch member is configured for lateral mounting to the modular component.
- 5. (Previously Presented) The attachment system of claim 4, wherein the release member is configured for mounting to an accessible side of the modular component.
- 6. (Previously Presented) The attachment system of claim 5, wherein the release member is rotatably coupled to the latch member.

- 7. (Previously Presented) The attachment system of claim 1, wherein the latch member and the release member each comprise a fixed end configured for coupling to adjacent sides of the modular component.
- 8. (Previously Presented) The attachment system of claim 7, wherein the latch member and the release member are rotatably coupled at opposite ends from the fixed ends.
- 9. (Previously Presented) The attachment system of claim 1, wherein the release member is bowable to a substantially curved geometry at the released position.
 - 10. (Currently Amended) A modular component for a computer system, comprising: a modular housing comprising an accessible side and a lateral side;
 - a low profile latch coupled to the lateral side; and
- a bowable and graspable release member coupled to the accessible side and hingedly movably-coupled to the low profile latch.
- 11. (Original) The modular component of claim 10, wherein the modular housing comprises a cooling device.
- 12. (Original) The modular component of claim 10, wherein the modular housing comprises a memory device.
- 13. (Original) The modular component of claim 10, wherein the modular housing comprises electronic circuitry.
- 14. (Original) The modular component of claim 13, wherein the electronic circuitry comprises an electrical plug movably coupled to the modular housing.

- 15. (Previously Presented) The modular component of claim 10, wherein the bowable and graspable release member is outwardly pullable and bowable to a narrower width dimension.
- 16. (Previously Presented) The modular component of claim 15, wherein the low profile latch is inwardly releasable with bowing of the bowable and graspable release member.

Claims 17-20 (Canceled)

- 21. (Currently Amended) A mounting apparatus, comprising:
- a tool-free coupling movable between secured and released positions; and
- a bending-activated release coupled to the tool-free coupling and configured to move the tool-free coupling between the latched and released positions in both directions.
- 22. (Previously Presented) The mounting apparatus of claim 21, wherein the tool-free coupling comprises an elongated flexible member having a latch.
- 23. (Previously Presented) The mounting apparatus of claim 22, wherein the elongated flexible member comprises a substantially flat structure having a fixed end and a movable end coupled to the bending-activated release.
- 24. (Previously Presented) The mounting apparatus of claim 21, wherein the bending-activated release is disposed in a first plane and the tool-free coupling is disposed in a second plane inaccessible from the first plane during mounting.
- 25. (Previously Presented) The mounting apparatus of claim 21, wherein the bending-activated release and the tool-free coupling comprises first and second low-profile flexible members disposed in first and second planes, respectively.

- 26. (Previously Presented) The mounting apparatus of claim 25, wherein the first and second low-profile flexible members each comprise a fixed end and a movable end, wherein the movable ends are coupled near the intersection of the first and second planes.
 - 27. (Currently Amended) A mounting method, comprising:
 - providing a tool-free coupling <u>substantially located at a first side of a device and</u> operable at an inaccessible interface between <u>the a-device</u> and a mounting receptacle; and
 - providing a flex-activated release <u>substantially located at a second side of the device</u>

 <u>and configured operable at an accessible side of the device</u> to facilitate disengagement of the tool-free coupling, <u>wherein the second side is different</u> than the first side.
- 28. (Previously Presented) The mounting method of claim 27, comprising mounting the device in the mounting receptacle.
- 29. (Previously Presented) The mounting method of claim 27, comprising mounting a plurality of computer components in adjacent mounting receptacles, wherein each of the computer components comprises the tool-free coupling and the flex-activated release.
- 30. (Previously Presented) The mounting method of claim 27, comprising mounting a plurality of redundant cooling fans each having the tool-free coupling and the flex-activated release.
- 31. (Previously Presented) The mounting method of claim 27, comprising dismounting the device from the mounting receptacle via flexing the flex-activated release to disengage the tool-free coupling.

- 32. (Previously Presented) The mounting method of claim 31, wherein flexing comprises manually inducing bowing of the flex-activated release to provide a lateral displacement corresponding to a reduced width of the flex-activated release.
- 33. (Previously Presented) The mounting method of claim 31, wherein flexing comprises pulling the flex-activated release.
- 34. (Previously Presented) The mounting method of claim 33, wherein pulling comprises moving the tool-free coupling to a disengaged position and providing a removal force to remove the device from the mounting receptacle.